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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Ken Chen

Serial No.: 10/058,473

Filed: 01/28/2002

For: ENHANCED ADHESION STRENGTH  
BETWEEN MOLD RESIN AND POLYIMIDE

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)  
) Group Art Unit: 2823  
)  
) Examiner: Toledo, Fernando  
)  
) Confirmation No.: 4186  
)  
) TKHR Docket: 252016-1040  
) Top-Team: 0503-A30594US  
)

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment; Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on December 23, 2004.

Signature – Hui Chin Barnhill

**AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

The Office Action mailed October 6, 2004 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

**Amendments to the Claims** begin on page 2; **Remarks** begin on page 10 of this paper.